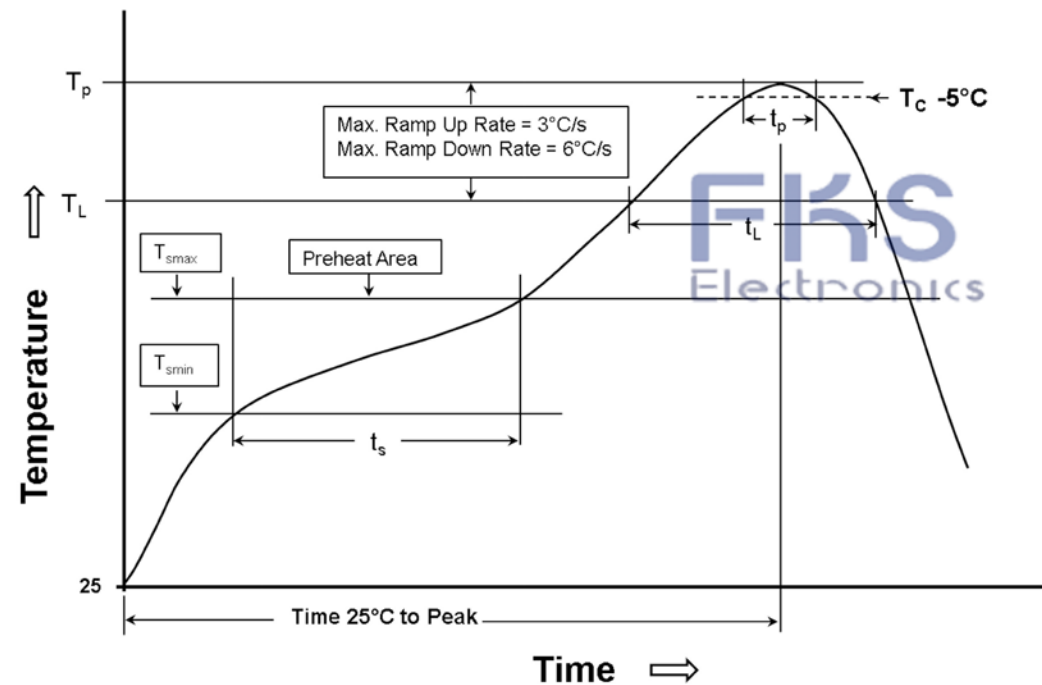


H Soldering Specifications:



H1: Classification Reflow Profile for SMT components:



H2: Classification Reflow Profiles

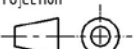
Profile Feature	Pb-Free Assembly
Preheat - Temperature Min (T_{smin}) - Temperature Max (T_{smax}) - Time (t_s) from (T_{smin} to T_{smax})	150°C 200°C 60-120 seconds
Ramp-up rate (T_L to T_p)	3°C/ second max.
Liquidous temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Peak package body temperature (T_p)	See Table H3
Time within 5°C of actual peak temperature (t_p)	20-30 seconds
Ramp-down rate (T_p to T_L)	6°C/ second max.
Time 25°C to peak temperature	8 minutes max.

refer to IPC/JEDEC J-STD-020D

H3: Package Classification Reflow Temperature

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
PB-Free Assembly	< 1.6 mm	260°C	260°C	260°C
PB-Free Assembly	1.6 - 2.5 mm	260°C	250°C	245°C
PB-Free Assembly	≥ 2.5 mm	250°C	245°C	245°C

refer to IPC/JEDEC J-STD-020D

				Projection 		DESCRIPTION SMD Wire Wound Inductor		
	2015-07-01							
				Shaanxi FKS Electronic Parts Import&Export Co.,Ltd. FKS(Xi'an) Electronic Technology Co.,Ltd. Address: B1 Building,Western Cloud Valley,Fengxi New Town, Xixian New Area,Xi'an City, Shaanxi Province,China. Tel: +86-29-8868 5333 Fax: +86-29-8868 0913 	Order.- No. FKS744776360	COMPLIANT RoHS&REACH	SIZE A4	
	DATE					Size: Type M (Actuator)		

Size: Type M (Actuator)

Size: Type M (Actuator)